PERMATECH ELECTRONICS CORPORATION

Conflict Minerals Policy

There has been increased awareness of violence and human rights violations in the mining of certain minerals from the Democratic Republic of the Congo (DRC) and surrounding countries. Permatech Electronics shares the deep concern about sources of minerals from these conflict zones and is therefore committed to make our products and manufacturing process DRC conflict-free and obtain full transparency throughout our supply chain.

Section 1502 of the Dodd-Frank Wall Street Reform and Consumer Protection Act (the Act) enacted in July 2010 imposes new supply chain reporting requirements on publicly traded companies to promote transparency and consumer awareness regarding the use of "conflict minerals" columbite-tantalite (coltan), cassiterite, gold, wolframite, or their derivatives (tantalum, tin, gold and tungsten) that directly or indirectly finance or benefit armed groups in that region. As directed by the Act, the U.S. Securities and Exchange Commission (SEC) has adopted rules requiring publicly traded companies to disclose whether they use tantalum, tin, gold and tungsten that originated in the DRC and if so, to issue a report identifying their products that are not conflict free and their due diligence efforts to determine the source and chain of custody of the metals.

As part of this commitment, Permatech will exercise due diligence on all its Suppliers/Distributors of these minerals in accordance with the OECD Due Diligence Guidance for Responsible Supply Chains of Minerals from Conflict-Affected and High-Risk areas. Under this policy, Permatech expects all its suppliers to:

1. Conduct their business in conformance with the EICC Code of Conduct requirements.
2. Exclusively source from smelters or refineries that have been independently audited and approved as "conflict-free" by the Conflict-Free Smelter Program or equivalent.
3. Exercise due diligence on their supply chains in accordance with the OECD Due Diligence Guidance and the EICC Code of Conduct.

There are some materials which contain metals such as gold, tin and tantalum are used in our products and manufacturing process. They are:

1. PCB Assembly -- Soldering material (Solder Bar, Paste, Wire) -- TIN
2. Components -- Passive chip, IC, Connector, etc. – TIN, GOLD and TANTALU

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